

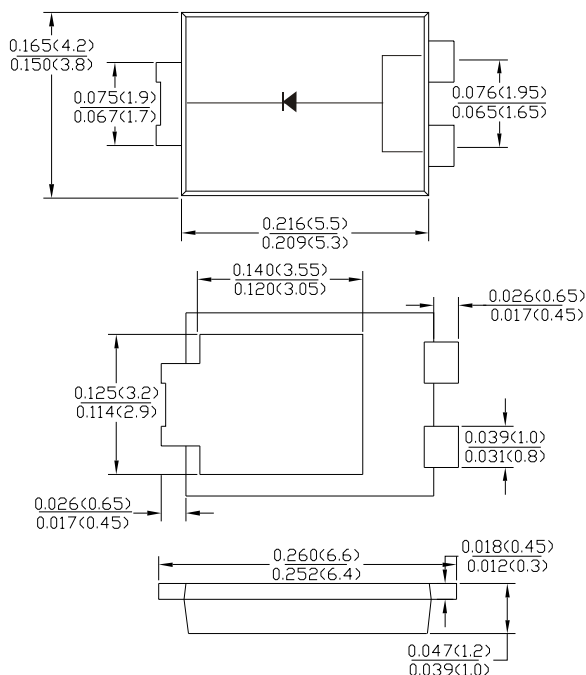
Features

- Schottky Barrier Chip
- High Thermal Reliability
- Patented Super Barrier Rectifier Technology
- High Forward Surge Capability
- Ultra Low Power Loss, High Efficiency
- Excellent High Temperature Stability
- Plastic material-UL flammability 94V-0

Mechanical Data

- Case: TO-277, molded plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Mounting Position: Any
- Marking: Type Number
- Lead Free: For RoHS/Lead Free Version

TO-277



Dimensions inches and (milimeters)

Maximum Ratings and Electrical Characteristics @T_A =25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbol	SL 1545	SL 1550	SL 1560	SL 1580	SL 15100	SL 15150	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	45	50	60	80	100	150	V
Working Peak Reverse Voltage	V _{RWM}							
DC blocking voltage	V _{DC}							
RMS Rectified Voltage	V _{R(RMS)}	28	35	42	56	70	105	V
Average Rectified Output Current (Note1)	I _o	15						A
Non-Repetitive Peak Forward Surge8.3ms	I _{FSM}	275						A
Single Half Sine-Wave Superimposed on rated load(JEDEC Method) (Note2)								
Forward Voltage Drop T _A =25°C @ IF=15A	V _{FM}	0.48	0.50	0.55	0.75		0.80	V
Peak Reverse Curent T _A =25°C At Rated DC Blocking Voltage T _A =100 °C	I _R	0.3 15						mA
Typical Thermal Resistance	R _{θJA}	80						°C/W
Junctionto Ambient	R _{θJL}	15						
Operating junction temperature range	T _J	-55 to +150						°C
storage temperature range	T _{STG}	-55 to +150						°C

Note: 1. Valid Provided that are kept at ambient temperature at a distance of 9.5mm from the case.

2. Fr-4 PCB, 2oz. Copper, minimum recommended pad layout: 18.8mm x 14.4mm. Anode pad dimensions 5.6mm x 14.4mm.

Fig.1 - Forward Current Derating Curve

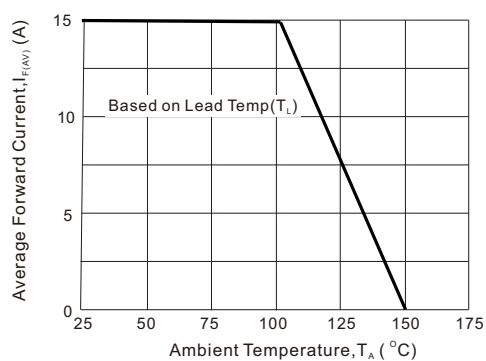


Fig2 : Instantaneous Forward Voltage

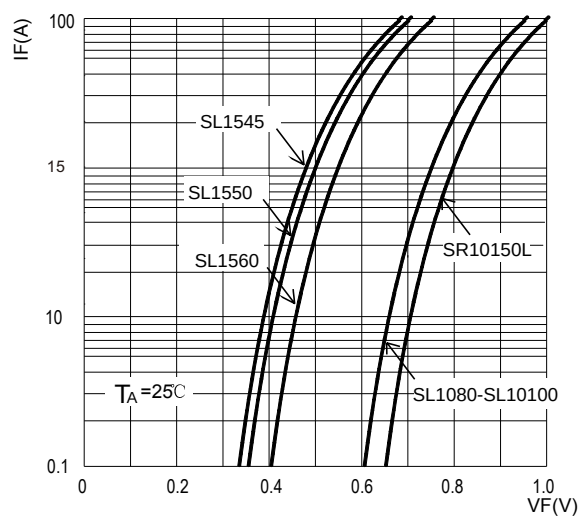


Fig3: Surge Forward Current Capability

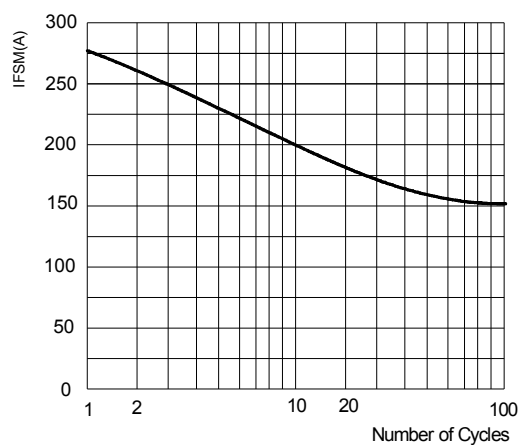


Fig4: Typical Reverse Characteristics

